



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	26-07-2017
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F7331EK6	P4MR*452XXXA	A	9996	26-07-2017
Amount	UoM	Unit type	ST ECOPACK Grade	
112,20	mg	Each	ECOPACK® 2	
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	NAC	Copper Alloy		



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Package Designator	Size	Nbr of instances	Shape	
BGA	10x10x0,6	201	No lead	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P4MR*452XXXX				7000000.0	1000000.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	4,653	mg	supplier	die	Silicon (Si)	7440-21-3		3,678	mg	790458	32781				
				supplier	metallization	Aluminium (Al)	7429-90-5		0,068	mg	14614	606				
				supplier	metallization	Copper (Cu)	7440-50-8		0,443	mg	95207	3948				
				supplier	metallization	Cobalt (Co)	7440-48-4		0,001	mg	215	9				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0,062	mg	13325	553				
				supplier	metallization	Tungsten (W)	7440-33-7		0,199	mg	42768	1774				
				supplier	Passivation	Silicon Nitride	12033-89-5		0,052	mg	11176	463				
				supplier	Passivation	Silicon Oxide	7631-86-9		0,150	mg	32237	1337				
				SILICON DIE	M-011 Other inorganic materials	3,678	mg	supplier	DIE	Silicon (Si)	7440-21-3		3,678	mg	1000000	32783
				SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	41,947	mg	supplier	CORE	Glass Cloth	65997-17-3		3,561	mg	84900	31740
				supplier	CORE	Epoxy resin	61788-97-4		0,839	mg	20000	7477				
				supplier	CORE	Flame resistant epoxy resin	223769-10-6		0,839	mg	20000	7477				
				supplier	CORE	Heat resistant resin	25722-66-1		0,839	mg	20000	7477				
				supplier	CORE	Silica filler	7631-86-9		2,093	mg	49900	18655				
				supplier	CORE	Metal Hydroxide	Proprietary		0,210	mg	5000	1869				
				supplier	COPPER FOIL	Copper (Cu)	7440-50-8		8,377	mg	199700	74659				
				supplier	SOLDERMASK (AUS308)	Talc containing no asbestiform fibers	14807-96-6		0,256	mg	6100	2281				
				supplier	SOLDERMASK (AUS308)	Barium sulfate	7727-43-7		4,128	mg	98400	36787				
				supplier	SOLDERMASK (AUS308)	Dipropylene monomethyl ether	34590-94-8		1,221	mg	29100	10879				
				supplier	SOLDERMASK (AUS308)	Naphthalene	91-20-3		0,126	mg	3000	1122				
				supplier	SOLDERMASK (AUS308)	Morpholine derivative	Proprietary		0,629	mg	15000	5608				
				supplier	CU PLATING	Copper (Cu)	7440-50-8		16,133	mg	384600	143785				
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		2,412	mg	57500	21497				
				supplier	AU PLATING	Gold (Au)	7440-57-5		0,285	mg	6800	2542				
DIE ATTACH (ATB-130U)	M-011 Other inorganic materials	0,528	mg	supplier	GLUE	Butadiene,acrylonitrile polymer,carboxy-termin	68610-41-3		0,369	mg	700000	3292				
				supplier	GLUE	Phenol-formaldehyde polymer	9003-35-4		0,053	mg	100000	470				
				supplier	GLUE	Phenol polymer with formaldehyde,glycidyl et	28064-14-4		0,049	mg	92000	433				
				supplier	GLUE	Dapsone	80-08-0		0,051	mg	97000	456				
				supplier	GLUE	Reaction product bisphenol-A-(epichlorhydrin)	25068-38-6		0,005	mg	10000	47				
				supplier	GLUE	4,4, Isopropylidenediphenol	80-05-7		0,001	mg	1000	5				
BONDING WIRE (MKE 4N)	M-011 Other inorganic materials	2,417	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		2,417	mg	1000000	21545				
SOLDERBALL (Sn96.5Ag3.5)	M-011 Other inorganic materials	6,241	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		6,023	mg	965000	53680				
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0,218	mg	35000	1947				
ENCAPSULATION (GE-100LFC5)	M-011 Other inorganic materials	52,736	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		46,997	mg	900000	418867				
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		2,582	mg	45000	23017				
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		2,296	mg	40000	20460				
				supplier	MOLDING COMPOUND	Metal Hydroxide	Proprietary		0,574	mg	10000	5115				
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0,287	mg	5000	2557				